**LM828 Switched Capacitor Voltage Converter**

Check for Samples: LM828

**FEATURES**
- Inverts Input Supply Voltage
- SOT-23 Package
- 20Ω Typical Output Impedance
- 97% Typical Conversion Efficiency at 5 mA

**APPLICATIONS**
- Cellular Phones
- Pagers
- PDAs
- Operational Amplifier Power Supplies
- Interface Power Supplies
- Handheld Instruments

**DESCRIPTION**

The LM828 CMOS charge-pump voltage converter inverts a positive voltage in the range of +1.8V to +5.5V to the corresponding negative voltage of −1.8V to −5.5V. The LM828 uses two low cost capacitors to provide up to 25 mA of output current.

The LM828 operates at 12 kHz switching frequency to reduce output resistance and voltage ripple. With an operating current of only 40 µA (operating efficiency greater than 96% with most loads), the LM828 provides ideal performance for battery powered systems. The device is in a tiny SOT-23 package.

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**Basic Application Circuits**

### Voltage Inverter

**+5V to −10V Converter**

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All trademarks are the property of their respective owners.
These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

### Absolute Maximum Ratings\(^{(1)(2)}\)

| Supply Voltage (V+ to GND, or GND to OUT) | 5.8V |
| V+ and OUT Continuous Output Current | 50 mA |
| Output Short-Circuit Duration to GND\(^{(3)}\) | 1 sec. |
| Continuous Power Dissipation (\(T_A = 25°C\))\(^{(4)}\) | 240 mW |
| \(T_{J\text{Max}}\)\(^{(4)}\) | 150°C |
| \(\theta_{JA}\)\(^{(4)}\) | 300°C/W |
| Operating Junction Temperature Range | −40°C to 85°C |
| Storage Temperature Range | −65°C to +150°C |
| Lead Temp. (Soldering, 10 seconds) | 300°C |
| ESD Rating\(^{(5)}\) | 2kV |

(1) Absolute maximum ratings indicate limits beyond which damage to the device may occur. Electrical specifications do not apply when operating the device beyond its rated operating conditions.

(2) If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/Distributors for availability and specifications.

(3) OUT may be shorted to GND for one second without damage. However, shorting OUT to V+ may damage the device and should be avoided. Also, for temperatures above 85°C, OUT must not be shorted to GND or V+, or the device may be damaged.

(4) The maximum allowable power dissipation is calculated by using \[ P_{\text{DMAX}} = \frac{(T_{J\text{Max}} - T_A)\theta_{JA}}{T_{J\text{Max}}} \]

(5) The human body model is a 100 pF capacitor discharged through a 1.5 kΩ resistor into each pin.

### Electrical Characteristics

Limits in standard typeface are for \(T_J = 25°C\), and limits in **boldface** type apply over the full operating temperature range. Unless otherwise specified: \(V_+ = 5V, C_1 = C_2 = 10 \mu F\).\(^{(1)}\)

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Condition</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Units</th>
</tr>
</thead>
<tbody>
<tr>
<td>V+</td>
<td>Supply Voltage</td>
<td>(R_L = 10k\Omega)</td>
<td>1.8</td>
<td>5.5</td>
<td>V</td>
<td></td>
</tr>
<tr>
<td>(I_Q)</td>
<td>Supply Current</td>
<td>No Load</td>
<td>40</td>
<td>75</td>
<td>(\mu A)</td>
<td></td>
</tr>
<tr>
<td>(R_{OUT})</td>
<td>Output Resistance(^{(2)})</td>
<td>(I_L = 5 \text{ mA})</td>
<td>20</td>
<td>65</td>
<td>(\Omega)</td>
<td></td>
</tr>
<tr>
<td>(f_{OSC})</td>
<td>Oscillator Frequency(^{(3)})</td>
<td>Internal</td>
<td>12</td>
<td>24</td>
<td>56</td>
<td>kHz</td>
</tr>
<tr>
<td>(f_{SW})</td>
<td>Switching Frequency(^{(3)})</td>
<td>Measured at CAP+</td>
<td>6</td>
<td>12</td>
<td>28</td>
<td>kHz</td>
</tr>
<tr>
<td>(P_{EFF})</td>
<td>Power Efficiency</td>
<td>(I_L = 5 \text{ mA})</td>
<td>97</td>
<td></td>
<td>%</td>
<td></td>
</tr>
<tr>
<td>(V_{OEFF})</td>
<td>Voltage Conversion Efficiency</td>
<td>No Load</td>
<td>95</td>
<td>99.96</td>
<td>%</td>
<td></td>
</tr>
</tbody>
</table>

(1) In the test circuit, capacitors \(C_1\) and \(C_2\) are 10 \(\mu F\), 0.3Ω maximum ESR capacitors. Capacitors with higher ESR will increase output resistance, reduce output voltage and efficiency.

(2) Specified output resistance includes internal switch resistance and capacitor ESR. See the details in the application information.

(3) The output switches operate at one half of the oscillator frequency, \(f_{OSC} = 2f_{SW}\).
Test Circuit

*C1 and C2 are 10 μF capacitors.

Figure 1. LM828 Test Circuit

Typical Performance Characteristics
(Circuit of Figure 1, V+ = 5V unless otherwise specified)

Figure 2. Supply Current vs Supply Voltage

Figure 3. Supply Current vs Temperature

Figure 4. Output Source Resistance vs Supply Voltage

Figure 5. Output Source Resistance vs Temperature
Typical Performance Characteristics (continued)

(Circuit of Figure 1, V+ = 5V unless otherwise specified)

Output Voltage vs Load Current

![Figure 6. Output Voltage vs Load Current](image)

Efficiency vs Load Current

![Figure 7. Efficiency vs Load Current](image)

Switching Frequency vs Supply Voltage

![Figure 8. Switching Frequency vs Supply Voltage](image)

Switching Frequency vs Temperature

![Figure 9. Switching Frequency vs Temperature](image)

CONNECTION DIAGRAMS

5-Lead SOT-23 Package (DBV)

![Figure 10. SOT-23 Package – Top View](image)

Figure 10. SOT-23 Package – Top View
See Package Number DBV0005A

![Figure 11. Actual Size](image)

Figure 11. Actual Size
Pin Functions

PIN DESCRIPTIONS

<table>
<thead>
<tr>
<th>Pin</th>
<th>Name</th>
<th>Function</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>OUT</td>
<td>Negative voltage output.</td>
</tr>
<tr>
<td>2</td>
<td>V+</td>
<td>Power supply positive input.</td>
</tr>
<tr>
<td>3</td>
<td>CAP−</td>
<td>Connect this pin to the negative terminal of the charge-pump capacitor.</td>
</tr>
<tr>
<td>4</td>
<td>GND</td>
<td>Power supply ground input.</td>
</tr>
<tr>
<td>5</td>
<td>CAP+</td>
<td>Connect this pin to the positive terminal of the charge-pump capacitor.</td>
</tr>
</tbody>
</table>

Circuit Description

The LM828 contains four large CMOS switches which are switched in a sequence to invert the input supply voltage. Energy transfer and storage are provided by external capacitors. Figure 12 illustrates the voltage conversion scheme. When S₁ and S₃ are closed, C₁ charges to the supply voltage V+. During this time interval, switches S₂ and S₄ are open. In the second time interval, S₁ and S₃ are open; at the same time, S₂ and S₄ are closed, C₁ is charging C₂. After a number of cycles, the voltage across C₂ will be pumped to V+. Since the anode of C₂ is connected to ground, the output at the cathode of C₂ equals −(V+) when there is no load current. The output voltage drop when a load is added is determined by the parasitic resistance (R_{ds(on)} of the MOSFET switches and the ESR of the capacitors) and the charge transfer loss between capacitors.

Application Information

SIMPLE NEGATIVE VOLTAGE CONVERTER

The main application of LM828 is to generate a negative supply voltage. The voltage inverter circuit uses only two external capacitors as shown in the Basic Application Circuits. The range of the input supply voltage is 1.8V to 5.5V.

The output characteristics of this circuit can be approximated by an ideal voltage source in series with a resistance. The voltage source equals −(V+). The output resistance, R_{out}, is a function of the ON resistance of the internal MOSFET switches, the oscillator frequency, the capacitance and the ESR of both C₁ and C₂. Since the switching current charging and discharging C₁ is approximately twice as the output current, the effect of the ESR of the pumping capacitor C₁ will be multiplied by four in the output resistance. The output capacitor C₂ is charging and discharging at a current approximately equal to the output current, therefore, this ESR term only counts once in the output resistance. A good approximation of R_{out} is:

\[ R_{OUT} \approx 2R_{SW} + \frac{2}{f_{OSC} \times C_1} + 4ESR_{C1} + ESR_{C2} \]  

(1)

where R_{SW} is the sum of the ON resistance of the internal MOSFET switches shown in Figure 12.

High capacitance, low ESR capacitors will reduce the output resistance.

The peak-to-peak output voltage ripple is determined by the oscillator frequency, the capacitance and ESR of the output capacitor C₂.
\[ V_{\text{RIPPLE}} = \frac{i_L}{f_{\text{OSC}} \times C_2} + 2 \times i_L \times \text{ESR}_{C2} \]  

(2)

Again, using a low ESR capacitor will result in lower ripple.

CAPACITOR SELECTION

The output resistance and ripple voltage are dependent on the capacitance and ESR values of the external capacitors. The output voltage drop is the load current times the output resistance, and the power efficiency is

\[ \eta = \frac{P_{\text{OUT}}}{P_{\text{IN}}} = \frac{i_L^2R_L}{i_L^2R_L + i_L^2R_{\text{OUT}} + i_Q(V+)} \]  

(3)

Where \( i_Q(V+) \) is the quiescent power loss of the IC device, and \( i_L^2R_{\text{OUT}} \) is the conversion loss associated with the switch on-resistance, the two external capacitors and their ESRs.

The selection of capacitors is based on the specifications of the dropout voltage (which equals \( i_{\text{out}}R_{\text{out}} \)), the output voltage ripple, and the converter efficiency. Low ESR capacitors (following table) are recommended to maximize efficiency, reduce the output voltage drop and voltage ripple.

<table>
<thead>
<tr>
<th>Manufacturer</th>
<th>Phone</th>
<th>Capacitor Type</th>
</tr>
</thead>
<tbody>
<tr>
<td>Nichicon Corp.</td>
<td>(708)-843-7500</td>
<td>PL &amp; PF series, through-hole aluminum electrolytic</td>
</tr>
<tr>
<td>AVX Corp.</td>
<td>(803)-448-9411</td>
<td>TPS series, surface-mount tantalum</td>
</tr>
<tr>
<td>Sprague</td>
<td>(207)-324-1410</td>
<td>593D, 594D, 595D series, surface-mount tantalum</td>
</tr>
<tr>
<td>Sanyo</td>
<td>(619)-661-6835</td>
<td>OS-CON series, through-hole aluminum electrolytic</td>
</tr>
<tr>
<td>Murata</td>
<td>(800)-831-9172</td>
<td>Ceramic chip capacitors</td>
</tr>
<tr>
<td>Taiyo Yuden</td>
<td>(800)-348-2496</td>
<td>Ceramic chip capacitors</td>
</tr>
<tr>
<td>Tokin</td>
<td>(408)-432-8020</td>
<td>Ceramic chip capacitors</td>
</tr>
</tbody>
</table>

Other Applications

PARALLELING DEVICES

Any number of LM828s can be paralleled to reduce the output resistance. Each device must have its own pumping capacitor \( C_1 \), while only one output capacitor \( C_{\text{OUT}} \) is needed as shown in Figure 13. The composite output resistance is:

\[ R_{\text{OUT}} = \frac{R_{\text{OUT}} \text{ of each } \text{LM828}}{\text{Number of Devices}} \]  

(4)

![Figure 13. Lowering Output Resistance by Paralleling Devices](image)
CASCADING DEVICES

Cascading the LM828s is an easy way to produce a greater negative voltage (e.g. A two-stage cascade circuit is shown in Figure 14).

If \( n \) is the integer representing the number of devices cascaded, the unloaded output voltage \( V_{\text{out}} \) is \((-nV_{\text{in}})\). The effective output resistance is equal to the weighted sum of each individual device:

\[
R_{\text{out}} = nR_{\text{out}_1} + \frac{n}{2}R_{\text{out}_2} + ... + R_{\text{out}_n}
\]

(5)

This can be seen by first assuming that each device is 100 percent efficient. Since the output voltage is different on each device the output current is as well. Each cascaded device sees less current at the output than the previous so the \( R_{\text{OUT}} \) voltage drop is lower in each device added. Note that, the number of \( n \) is practically limited since the increasing of \( n \) significantly reduces the efficiency, and increases the output resistance and output voltage ripple.

Figure 14. Increasing Output Voltage by Cascading Devices

COMBINED DOUBLER AND INVERTER

In Figure 15, the LM828 is used to provide a positive voltage doubler and a negative voltage converter. Note that the total current drawn from the two outputs should not exceed 40 mA.

Figure 15. Combined Voltage Doubler and Inverter
It is possible to regulate the negative output of the LM828 by use of a low dropout regulator (such as the LP2980). The whole converter is depicted in Figure 16. This converter can give a regulated output from $-1.8V$ to $-5.5V$ by choosing the proper resistor ratio:

$$V_{\text{out}} = V_{\text{ref}} \left(1 + \frac{R_1}{R_2}\right)$$

where, $V_{\text{ref}} = 1.23V$  \hspace{1cm} (6)

Note that the following conditions must be satisfied simultaneously for worst case design:

- $V_{\text{in}_{\text{min}}} > V_{\text{out}_{\text{min}}} + V_{\text{drop}_{\text{max}}} \text{ (LP2980)}$  \hspace{1cm} (8)
- $V_{\text{in}_{\text{max}}} < V_{\text{out}_{\text{max}}} + V_{\text{drop}_{\text{min}}} \text{ (LP2980)}$  \hspace{1cm} (10)
- $I_{\text{out}_{\text{max}}} \times R_{\text{out}_{\text{max}}} \text{ (LM828)}$  \hspace{1cm} (9)
- $I_{\text{out}_{\text{min}}} \times R_{\text{out}_{\text{min}}} \text{ (LM828)}$  \hspace{1cm} (11)

**Figure 16. Combining LM828 with LP2980 to Make a Negative Adjustable Regulator**
## REVISION HISTORY

<table>
<thead>
<tr>
<th>Changes from Revision C (May 2013) to Revision D</th>
<th>Page</th>
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<tr>
<td>• Changed layout of National Data Sheet to TI format</td>
<td>8</td>
</tr>
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## PACKAGING INFORMATION

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<tr>
<th>Orderable Device</th>
<th>Status</th>
<th>Package Type</th>
<th>Package Drawing</th>
<th>PIns</th>
<th>Package Qty</th>
<th>Eco Plan</th>
<th>Lead/Ball Finish</th>
<th>MSL Peak Temp</th>
<th>Op Temp (°C)</th>
<th>Device Marking</th>
<th>Samples</th>
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<tbody>
<tr>
<td>LM828M5</td>
<td>NRND</td>
<td>SOT-23</td>
<td>DBV</td>
<td>5</td>
<td>1000</td>
<td>TBD</td>
<td>Call TI</td>
<td>Call TI</td>
<td>-40 to 85</td>
<td>S08A</td>
<td>Samples</td>
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<td>LM828M5/NOPB</td>
<td>ACTIVE</td>
<td>SOT-23</td>
<td>DBV</td>
<td>5</td>
<td>1000</td>
<td>Green (RoHS &amp; no Sb/Br)</td>
<td>CU SN</td>
<td>Level-1-260C-UNLIM</td>
<td>-40 to 85</td>
<td>S08A</td>
<td>Samples</td>
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<tr>
<td>LM828M5X</td>
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<td>SOT-23</td>
<td>DBV</td>
<td>5</td>
<td>3000</td>
<td>TBD</td>
<td>Call TI</td>
<td>Call TI</td>
<td>-40 to 85</td>
<td>S08A</td>
<td>Samples</td>
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<tr>
<td>LM828M5X/NOPB</td>
<td>ACTIVE</td>
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<td>3000</td>
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<td>CU SN</td>
<td>Level-1-260C-UNLIM</td>
<td>-40 to 85</td>
<td>S08A</td>
<td>Samples</td>
</tr>
</tbody>
</table>

(1) The marketing status values are defined as follows:
- **ACTIVE:** Product device recommended for new designs.
- **LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
- **NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
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- **OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
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- **Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) **MSL, Peak Temp.** - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) **Lead/Ball Finish** - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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### TAPE AND REEL INFORMATION

#### REEL DIMENSIONS

![Reel Dimensions Diagram](image)

#### TAPE DIMENSIONS

A0 | Dimension designed to accommodate the component width  
B0 | Dimension designed to accommodate the component length  
K0 | Dimension designed to accommodate the component thickness  
W  | Overall width of the carrier tape  
P1 | Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

![Quadrant Assignments Diagram](image)

*All dimensions are nominal.*

<table>
<thead>
<tr>
<th>Device</th>
<th>Package Type</th>
<th>Package Drawing</th>
<th>Pins</th>
<th>SPQ</th>
<th>Reel Diameter (mm)</th>
<th>Reel Width W1 (mm)</th>
<th>A0  (mm)</th>
<th>B0  (mm)</th>
<th>K0  (mm)</th>
<th>P1  (mm)</th>
<th>W (mm)</th>
<th>Pin1 Quadrant</th>
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<tbody>
<tr>
<td>LM828M5</td>
<td>SOT-23</td>
<td>DBV</td>
<td>5</td>
<td>1000</td>
<td>178.0</td>
<td>8.4</td>
<td>3.2</td>
<td>3.2</td>
<td>1.4</td>
<td>4.0</td>
<td>8.0</td>
<td>Q2</td>
</tr>
<tr>
<td>LM828M5/NOPB</td>
<td>SOT-23</td>
<td>DBV</td>
<td>5</td>
<td>1000</td>
<td>178.0</td>
<td>8.4</td>
<td>3.2</td>
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<td>3.2</td>
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## TAPE AND REEL BOX DIMENSIONS

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<thead>
<tr>
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<th>Width (mm)</th>
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<tr>
<td>LM828M5</td>
<td>SOT-23</td>
<td>DBV</td>
<td>5</td>
<td>1000</td>
<td>210.0</td>
<td>185.0</td>
<td>35.0</td>
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<td>LM828M5/NOPB</td>
<td>SOT-23</td>
<td>DBV</td>
<td>5</td>
<td>1000</td>
<td>210.0</td>
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<td>210.0</td>
<td>185.0</td>
<td>35.0</td>
</tr>
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</table>

*All dimensions are nominal*
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